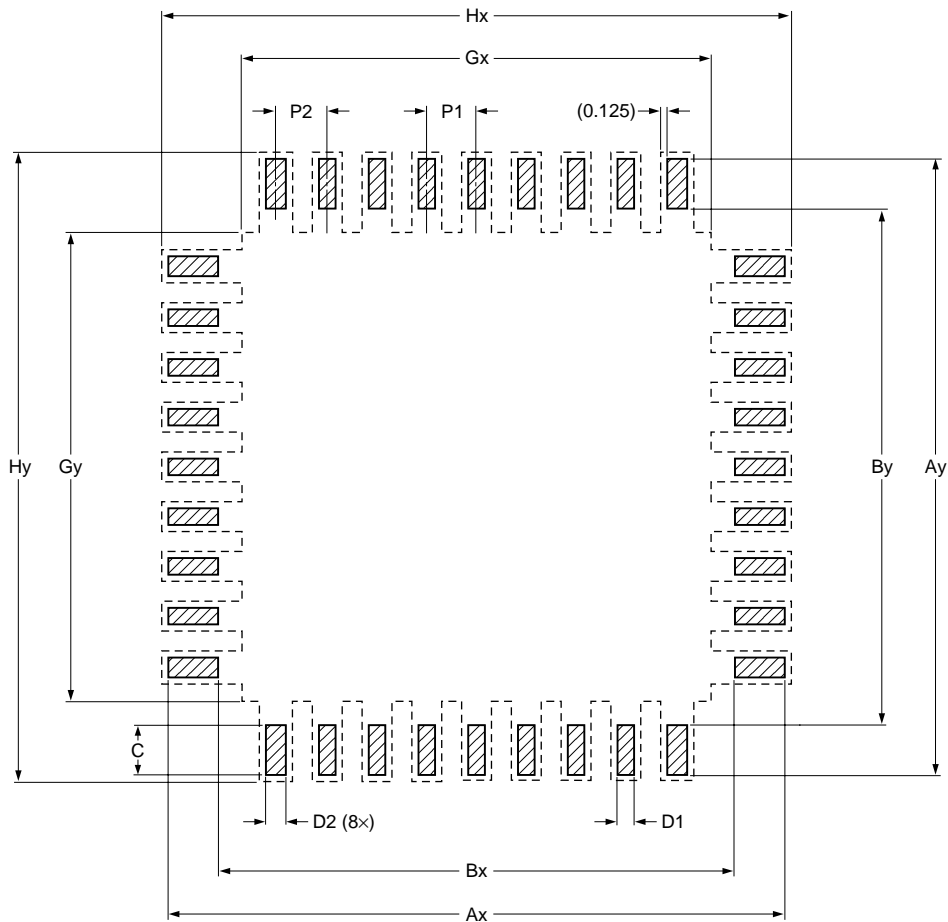


Footprint information for reflow soldering of QFP160 package

SOT322-2



Generic footprint pattern
Refer to the package outline drawing for actual layout

- solder land
- occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.650	0.700	31.900	31.900	28.900	28.900	1.500	0.400	0.500	28.500	28.500	32.150	32.150